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5th National Conference on Processing and Characterization of Materials

To cite this article: 2016 *IOP Conf. Ser.: Mater. Sci. Eng.* **115** 011001

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PREFACE

This volume contains selected full length technical papers from the oral presentations made during the 5th National Conference on Processing and Characterization of Materials (NCPCM) 2015 organized by Department of Metallurgical and Materials Engineering, NIT Rourkela, India on 12th-13th December, 2015. The first conference of the NCPCM series was held in December 2011. NCPCM 2015 has successfully carried the tradition of previous conferences. About 100 participants from various organizations across India have participated in the conference. The conference has attracted researchers, scientists and engineers from various R & D organizations, academic institutions and industries at a single forum. The interdisciplinary approach of the conference allowed the participants to look beyond their areas of activities. Besides oral presentations the conference also had poster and metallography sessions. The conference had four technical sessions. The themes of the sessions were: Materials Processing, Characterization, Materials Deformation and Materials Modelling and Simulation. In all, during the two day conference about fifty contributory talks along with four keynote lectures were presented. Out of these, forty peer-reviewed papers have been selected for publication in this volume of IOP Conference Series: Materials Science and Engineering.

We would like to thank all the contributors, members of the organizing committee, session chairs as well as colleagues and students who helped us with the preparation of the conference and particularly, with the preparation of this volume. We would also like to convey our heartiest gratitude to all the sponsors of NCPCM 2015.

February 2016

Editorial Board, NCPCM 2015







